



TDA10027HN

Dual cable demodulator with Out-Of Band receiver

Rev. 1 — 8 November 2011

Product short data sheet

1. General description

The TDA10027 is a Dual Cable Downstream Processor.

The Cable Downstream Processor (CDP) implements the physical interfaces and protocols required to provide the highest quality services of an in-band DOCSIS, EuroDOCSIS, DVB, and OpenCable Set-Top Box (STB). The downstream signals are digitized by 12-bit ADC and passed to the Demod and Forward Error Correction (FEC) blocks, which do all the cable physical layer processing. This processing includes demodulating and Annex A (Europe), Annex B (US) or Annex C (Japan) FEC for the in-band data.

The Out-Of Band (OOB) receiver consists of a QPSK demodulator with FEC, compliant to SCTE55-1 and SCTE55-2 standards, with either internal MAC or POD support. Data are digitized by a 10-bit ADC.

2. Features and benefits

- QPSK, 16 QAM, 32 QAM, 64 QAM, 128 QAM and 256 QAM Demodulator
- ITU-T J83 Annex A, B and C FEC
- Transport Stream Multiplex Frame (TSMF) module for Annex C compliance
- Time interleaved parallel mode or serial mode for Transport Stream (TS) interface
- On chip PLL for crystal frequency multiplication (16 MHz external)
- Reuse of the tuner clock, saving one crystal
- Embedded 12-bit ADC
- 3.3 V and 1.2 V power supplies
- Low power < 260 mW for dual stream operation
- Small size package
- Low cost Bill of Material
- OOB:
 - ◆ QPSK demodulator
 - ◆ SCTE55-1 and SCTE55-2 FEC
 - ◆ Embedded 10-bit ADC



3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
P	power dissipation	Standby mode: all 3 ADC in Power-down mode and all clocks disabled	-	10 ^[1]	30 ^[2]	mW
		operation mode: 1.2 V supply voltage; 2 simultaneous DVB-C demodulations (256 QAM 6.9 Msps) and 1 OOB SCTE55-1	-	225 ^[1]	305 ^[2]	mW
		3.3 V supply voltage; 2 simultaneous DVB-C demodulations (256 QAM 6.9 Msps) and 1 OOB SCTE55-1	-	35 ^[1]	55 ^[2]	mW
P _{tot}	total power dissipation	2 simultaneous DVB-C demodulations (256 QAM 6.9 Msps) and 1 OOB SCTE55-1	-	260 ^[1]	360 ^[2]	mW
V _{DD(1V2)}	supply voltage (1.2 V)		1.15	1.2	1.3	V
V _{DD(3V3)}	supply voltage (3.3 V)		3.0	3.3	3.6	V
V _{IH}	HIGH-level input voltage	V _{DD(3V3)} related input levels	2.0	-	V _{DD(3V3)} + 0.5	V
V _{IL}	LOW-level input voltage		-0.5	-	+0.8	V

[1] T_{amb} = 25 °C, V_{DD(1V2)} and V_{DD(3V3)} typical.

[2] T_j = 120 °C, V_{DD(1V2)} and V_{DD(3V3)} maximum.

4. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
TDA10027HN/C1	HVQFN64	plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 × 9 × 0.85 mm	SOT804-4

5. Block diagram

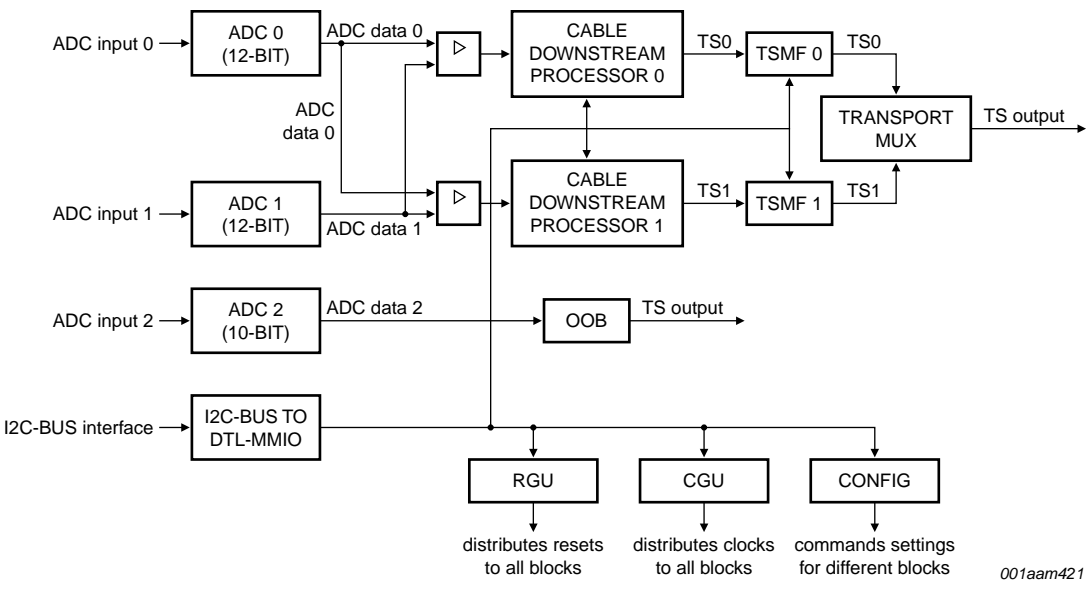


Fig 1. Block diagram

6. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
T _{stg}	storage temperature		-40	+150	°C
T _j	junction temperature		-	120	°C
V _{ESD}	electrostatic discharge voltage	EIA/JESD22-A114 (human body model)	2	-	kV
		EIA/JESD22-C101-C (FCDM)	[1] 0.5	-	kV

[1] It withstands class IV of JEDEC standard.

7. Abbreviations

Table 4. Abbreviations

Acronym	Description
ADC	Analog to Digital Converter
CDP	Cable Downstream Processor
CGU	Clock Generation Unit
DOCSIS	Data Over Cable Service Interface Specifications
DVB-C	Digital Video Broadcasting - Cable
FCDM	Field-Induced Charged-Device Model
FEC	Forward Error Correction
MAC	Media Access Control
OOB	Out-Of Band
PLL	Phase-Locked Loop
POD	Point Of Deployment
QAM	Quadrature Amplitude Modulation
QPSK	Quadrature Phase Shift Keying
RGU	Reset Generation Unit
STB	Set-Top Box
TS	Transport Stream
TSMF	Transport Stream Multiplex Frame
US	United States

8. Revision history

Table 5. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TDA10027HN_SDS v.1	20111108	Product short data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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